

Title (en)
PROPYLENE RESIN COMPOSITION

Title (de)
PROPYLEN-HARZ-ZUSAMMENSETZUNG

Title (fr)
COMPOSITION DE RÉSINE DE PROPYLÈNE

Publication
EP 3786229 A1 20210303 (EN)

Application
EP 19792956 A 20190424

Priority
• JP 2018083086 A 20180424
• JP 2019017324 W 20190424

Abstract (en)
Disclosed is a propylene-based resin composition comprising more than 15 parts by mass and 40 parts by mass or less of an ethylene/ α -olefin copolymer (E1) and 4 to 20 parts by mass of an ethylene/ α -olefin/diene copolymer (E2), and comprising also a propylene-based polymer (P1) having an amount of a n-decane-soluble part at 23°C of 5 to 25% by mass, wherein the ethylene content of the n-decane-soluble part is more than 40% by mass and 60% by mass or less, a propylene homopolymer (P2) and an inorganic filler (F) [providing that the total amount of the components (P1), (P2), (E1), (E2) and (F) is taken as 100 parts by weight]. The propylene-based resin composition is capable of producing a molded article which is excellent in mechanical properties, unnoticeable flow marks, low gloss.

IPC 8 full level
C08L 53/00 (2006.01); **C08K 3/013** (2018.01); **C08L 23/00** (2006.01); **C08L 23/08** (2006.01); **C08L 23/26** (2006.01)

CPC (source: EP US)
C08K 3/34 (2013.01 - US); **C08L 23/0815** (2013.01 - US); **C08L 23/083** (2013.01 - US); **C08L 23/12** (2013.01 - US); **C08L 23/14** (2013.01 - US); **C08L 53/00** (2013.01 - EP US); **C08L 2203/30** (2013.01 - US); **C08L 2205/02** (2013.01 - EP); **C08L 2205/025** (2013.01 - EP); **C08L 2205/03** (2013.01 - EP); **C08L 2205/035** (2013.01 - EP US)

Designated contracting state (EPC)
AL AT BE BG CH CY CZ DE DK EE ES FI FR GB GR HR HU IE IS IT LI LT LU LV MC MK MT NL NO PL PT RO RS SE SI SK SM TR

Designated extension state (EPC)
BA ME

DOCDB simple family (publication)
EP 3786229 A1 20210303; **EP 3786229 A4 20220112**; **EP 3786229 B1 20230726**; CN 112119122 A 20201222; CN 112119122 B 20221223; JP 7118140 B2 20220815; JP WO2019208601 A1 20210422; US 11434356 B2 20220906; US 2021246289 A1 20210812; WO 2019208601 A1 20191031

DOCDB simple family (application)
EP 19792956 A 20190424; CN 201980027545 A 20190424; JP 2019017324 W 20190424; JP 2020515503 A 20190424; US 201917049803 A 20190424